Radiation hardness of small-pitch 3D pixel sensors up to HL-LHC fluences

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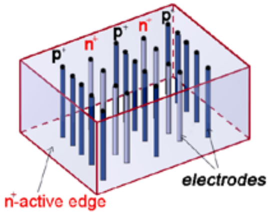
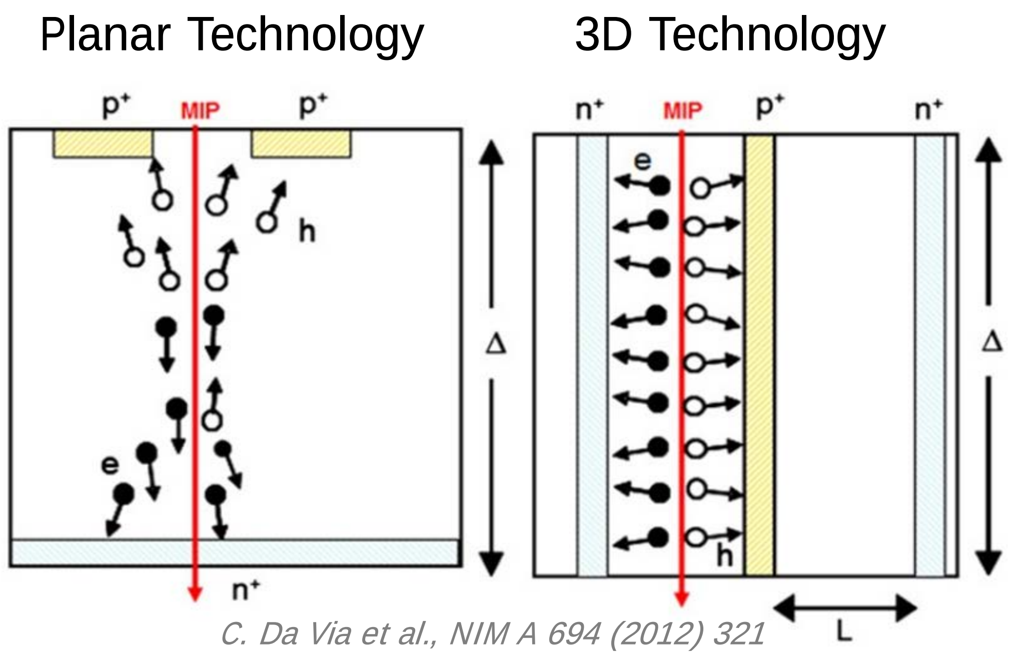
ATLAS

3D Detector Principle





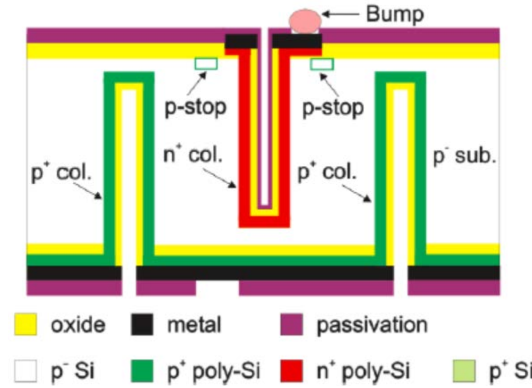
C. Da Via et al., NIM A 694 (2012) 321

Radiation-hard and active / slim-edge technology

- **Advantages**
  - Electrode distance decoupled from sensitive detector thickness
    → lower $V_{depletion}$
      → less power dissipation, cooling
    → smaller drift distance
      → faster charge collection
      → less trapping
  - Active or slim edges are natural feature of 3D technology
- **Challenges**
  - Complex production process
    → long production time
    → lower yields
    → higher costs
  - Higher capacitance
    → higher noise
  - Non-uniform response from 3D columns and low-field regions
    → small efficiency loss at 0°

Different 3D Technologies

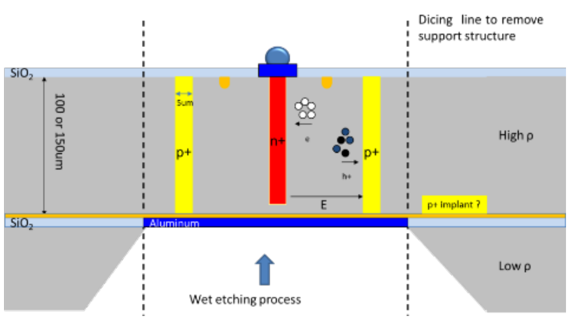
- Double sided (available at CNM)
  - IBL/AFP-proven technology
  - No handling wafers needed
    → thickness limited to ≥200 µm and wafers to 4”
  - 3D columns ~8 µm diameter



Double-sided

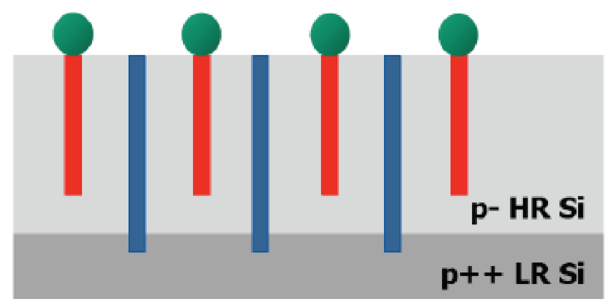
G. Pellegrini, CNM

- Single sided (available at FBK, SINTEF, CNM)
  - On handling wafer (SOI or Si-Si bonding)
    → 6” possible (FBK, SINTEF)
  - Active thickness range 50-150 µm being explored
  - Narrow 3D columns ~5 µm possible



SOI

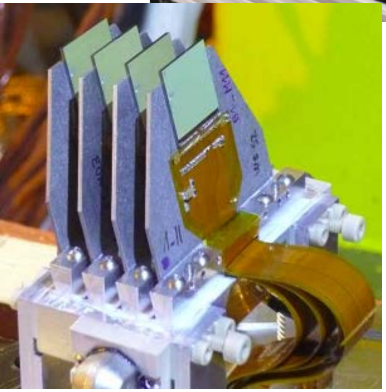
G. Pellegrini, CNM

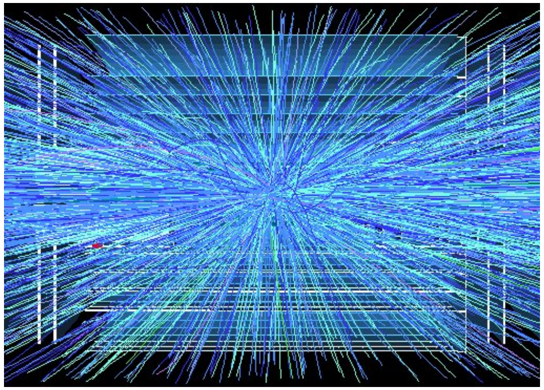


Si-Si bonding

M. Boscardin, FBK

Applications of 3D Silicon Pixel Detectors





- ATLAS IBL

  See talk by D. Fares

  - 25% 3D FEI4 detectors (CNM+FBK sensors)
  - Running since June 2015

- ATLAS Forward Proton (AFP)

  S. Grinstein et al., JINST 12 (2017) C01086

  - CNM sensors, 3D pixel modules produced by IFAE
  - Running in LHC since March 2016, upgraded in March 2017

- CMS-TOTEM PPS
  - CNM sensors
  - Installed in March 2017

- HL-LHC pixel detectors

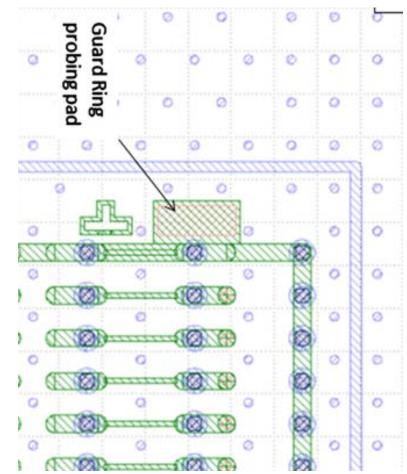
  This talk

  - Possible installation 2024, sensor qualification for Pixel TDRs 2017
  - Radiation hardness: 1-2e16 n_{eq}/cm^2 required
  - Reduced pixel size: 50x50 μm^2 or 25x100 μm^2
  - 3D promising candidate for innermost layer(s)

State of the Art: IBL/AFP Generation

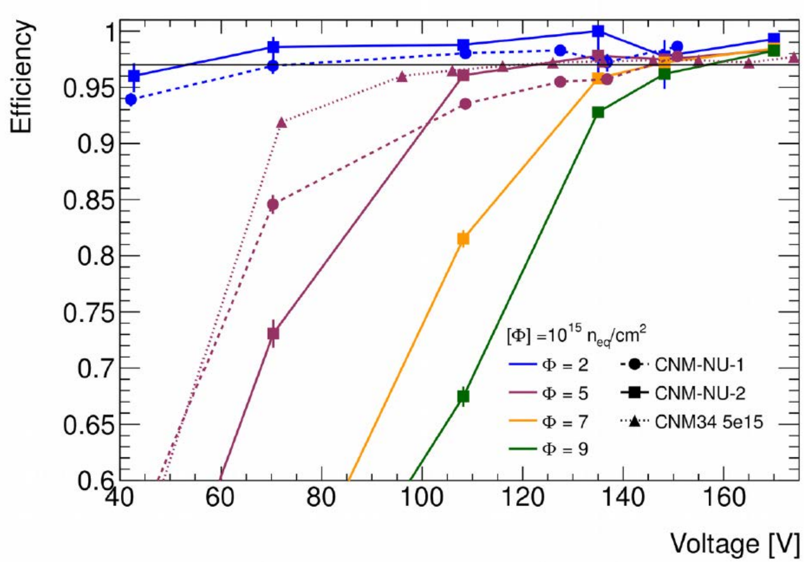
- 230 µm thick sensors by CNM and FBK (double-sided)
- FEI4s: 50x250 µm² 2E, 67 µm inter-el. distance
- Radiation hardness up to 5e15 n_{eq}/cm^2 established (IBL)
- Explored limits further with irradiations up to HL-LHC fluences
  - At 9.4e15 n_{eq}/cm^2 : 97.8% efficiency at 170 V!
  - Power dissipation 15 mW/cm² at 1e16 n_{eq}/cm^2 and -25°C

→ Good performance at HL-LHC fluences even for existing 3D generation

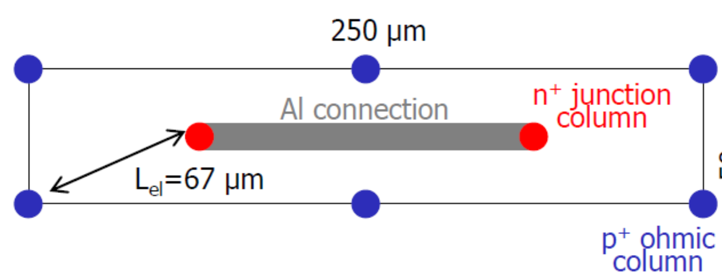


J. Lange et al., 2016 JINST 11 C11024

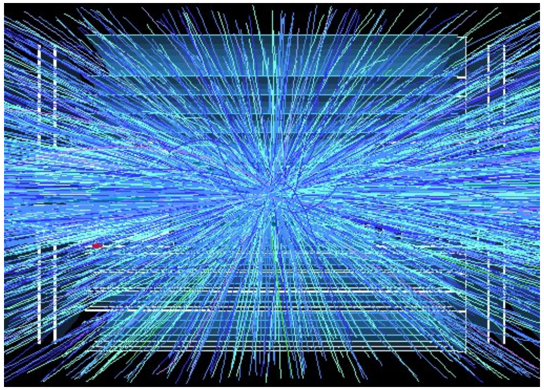
p-irradiated FEI4, 0° tilt



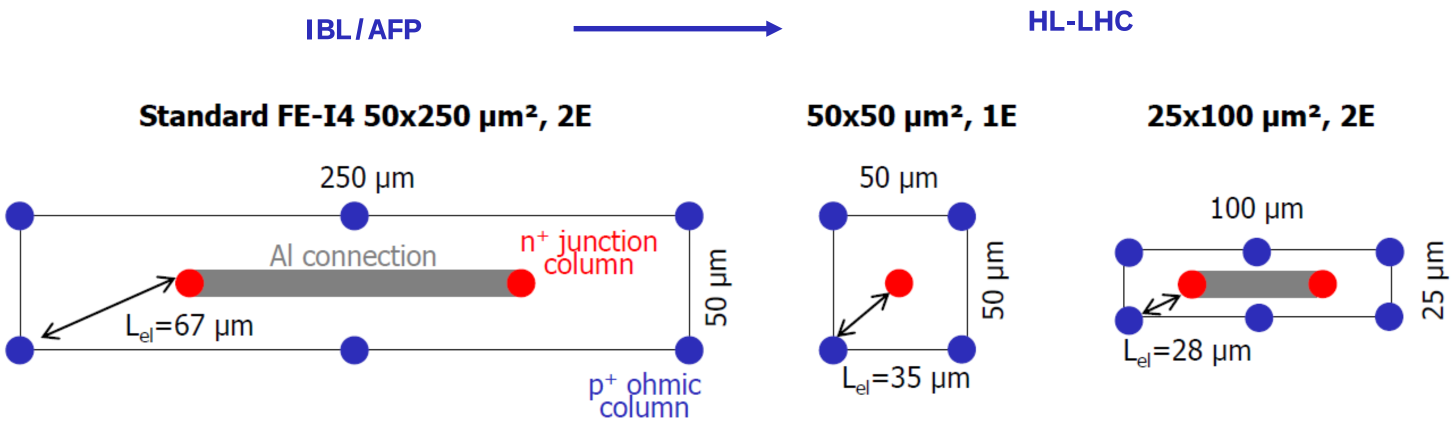
Standard FE-I4 50x250 µm², 2E



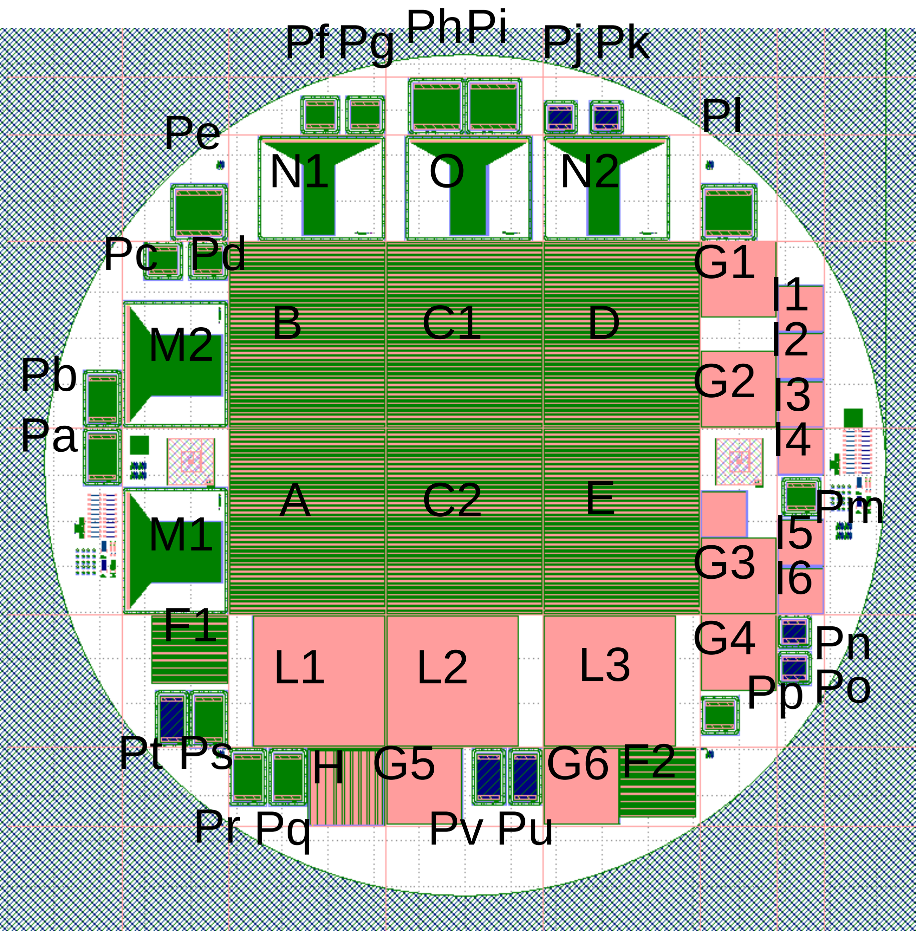
Development of HL-LHC 3D Pixel Detectors



- Radiation hardness: 1-2e16 n_{eq}/cm^2 required
- Reduced pixel size due to occupancy: 50x50 µm² or 25x100 µm²
  - RD53 readout chip under development
- Reduced 3D inter-electrode distance L_{el}
  → less trapping, V_{dep}
  → more radiation hard
  (but higher C_{det} and more dead material)
- Possibly reduced thickness (75-150 µm single-sided)
  - Lower occupancy, I_{leak}, C_{det} (but also lower signal)
  - But here only 230 µm studied



First Small-Pixel CNM Run for HL-LHC



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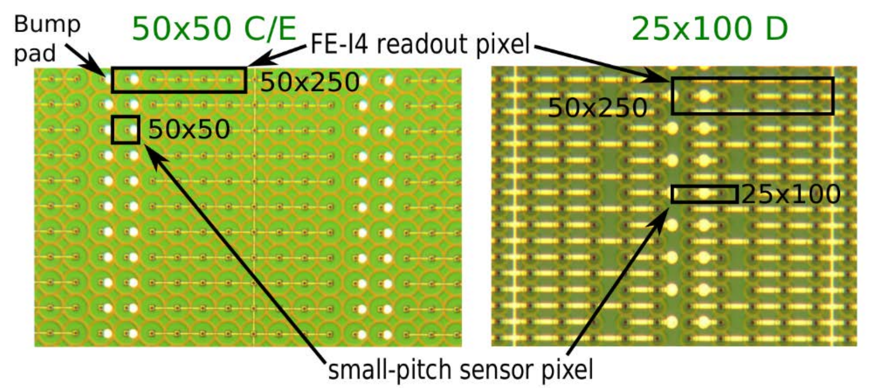
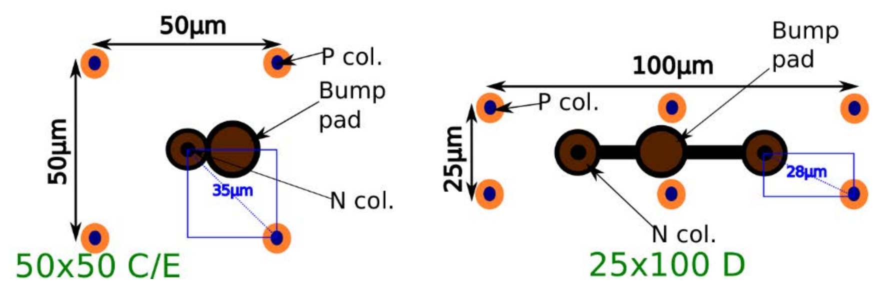
J. Lange et al., 2016 JINST 11 C11024

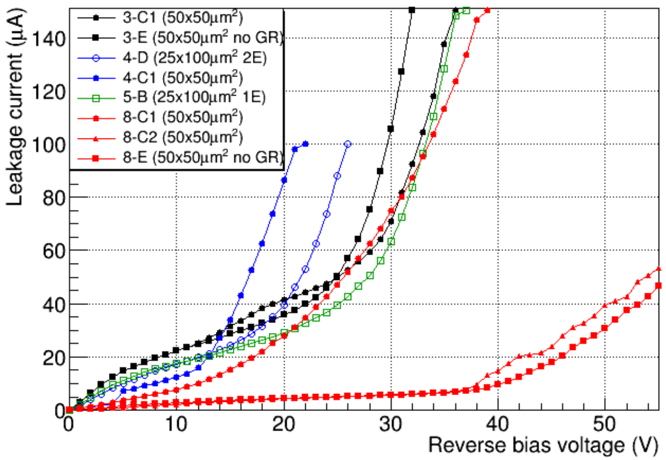
- Run 7781 finished in Dec 2015
- 5x 4" wafers, p-type, 230 µm double-sided, non-fully-passing-through columns (a la IBL)
- Increased aspect ratio 26:1 (column diameter 8 µm)
- **First time small pixel size 25x100+ 50x50 µm²** (folded into FEI4 and FEI3 geometries)
  - Also strips and diodes down to 25x25 µm² 3D unit cell





Sample Characterisations

Pixel IV



Pixel Geom.	C/el. [fF] (*)	C/pixel [fF] (*)	Noise [e]
25x100 2E	42	84	160
50x50 1E	37	37	105-140

(*) from pad diodes

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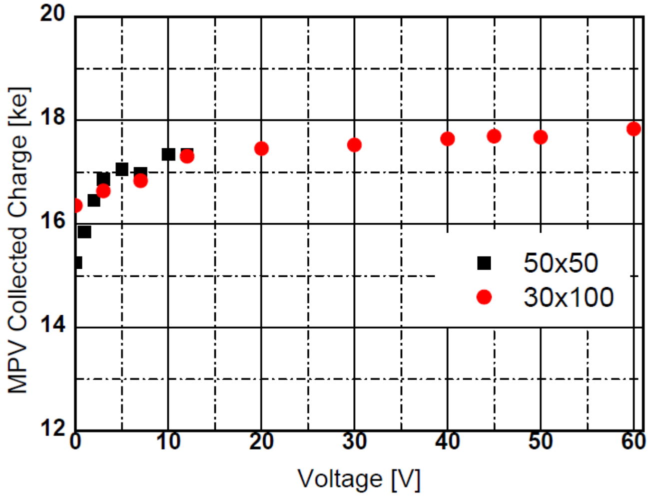
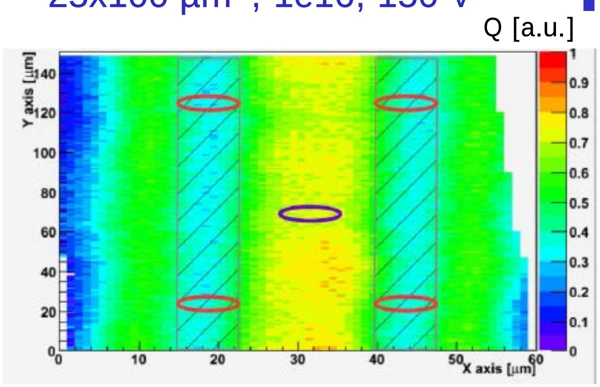
- Pixel devices bump-bonded and assembled at IFAE
- IVs
  - V_{BD} ~ 15-40 V
  - Improved in new productions after CNM process optimization
    S. Grinstein et al., JINST 12 (2017) C01086
- C <100 fF/pixel (within RD53 limit)
- Noise 100-160 e similar to standard 3D FEI4s
- Sr90 source scans on pixels
  - Similar charge as in standard FEI4s
- Sr90 and laser scans on strips
  - 17 ke charge as expected for both 50x50 μm² and 30x100 μm² (unirr.)
  - Almost full charge even at 0-2 V → low V_{dep} due to low L_{el}
  - Uniform even after 1e16 n_{eq}/cm²
  - Measurements up to 2e16 n_{eq}/cm² in progress

Strips charge collection (unirr.)



Strips laser scan
25x100 μm², 1e16, 150 V

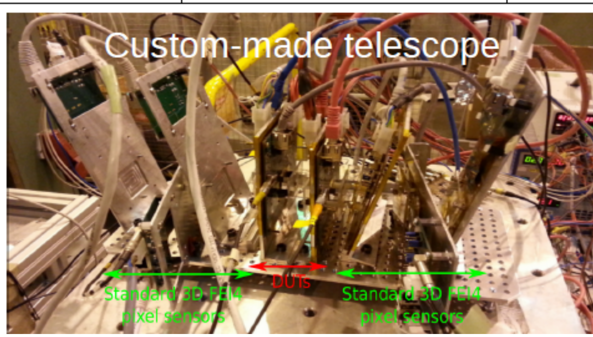


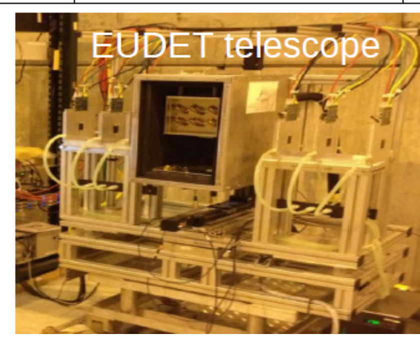
L. Simon

Beam Tests and Irradiations

- Irradiation at KIT (uniform) and PS IRRAD (non-uniform)
- Beam tests at CERN SPS H6, 120 GeV pions

Beam Test period	Telescope	Reconstruction framework	Sensor geometry (μm^2)	Irradiation (n_{eq}/cm^2)
May 2016	Custom-made 3D FEI4	Judith	50x50 + 25x100	Not irradiated
Nov 2016	EUDET	EUTelescope + TBmon2	50x50 + 50x50	5e15 (uniformly 23 MeV p^+ - KIT)
Sept 2016	EUDET	EUTelescope + TBmon2	50x50	1.4e16 (non uniformly 23 GeV p^+ - CERN PS)

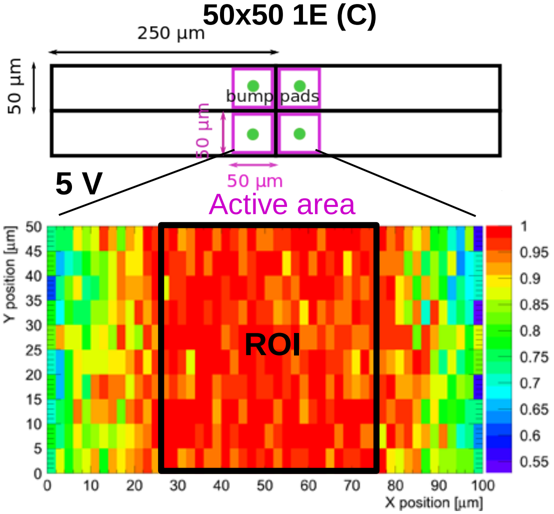




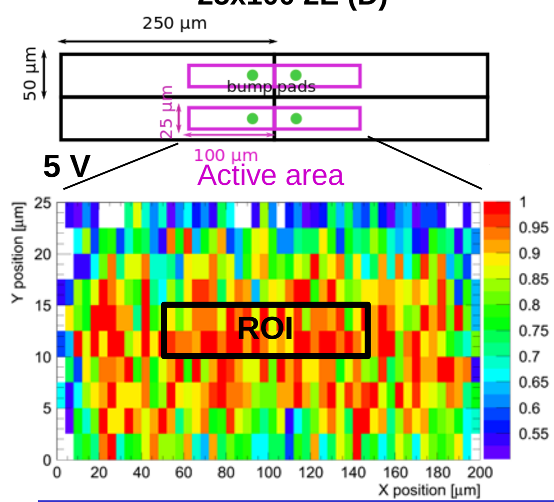
Efficiency before Irradiation

In-Pixel Efficiency (0˚ tilt)

50x50 1E (C)



25x100 2E (D)



- Select ROI within active region
  → avoid inactive area + telescope smearing
- Efficiency in ROI
  - 97% already from 1 V at 0°: very early depleted due to small electrode distance
  - Improvable by tilting: avoids hitting only low-efficiency regions

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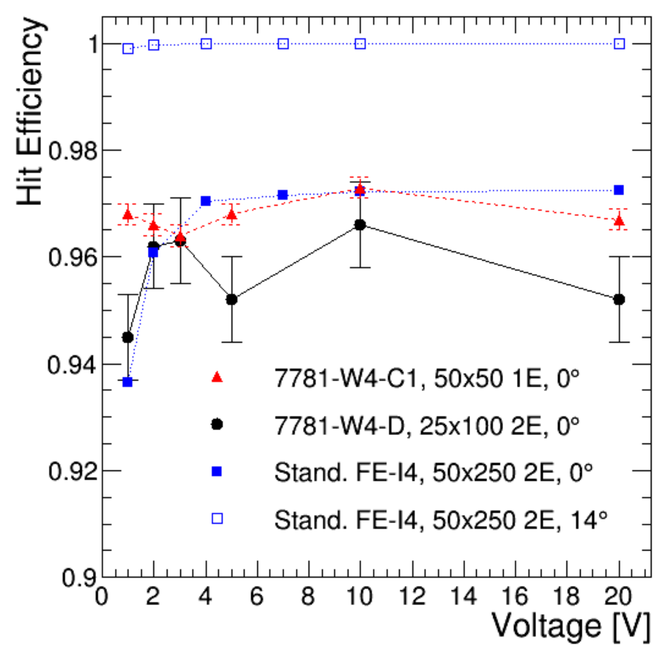
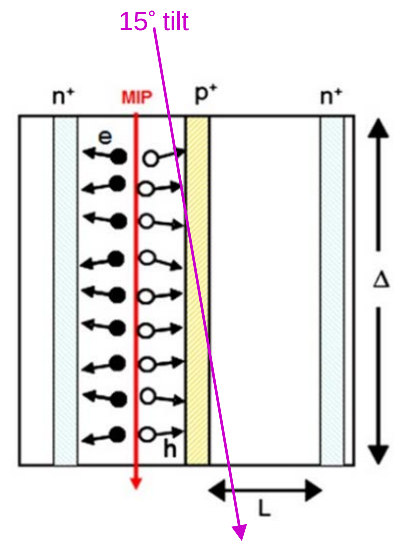
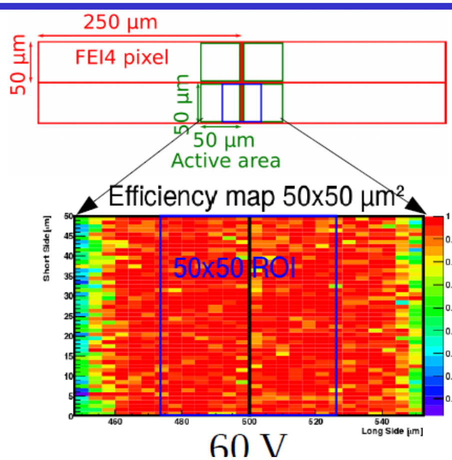
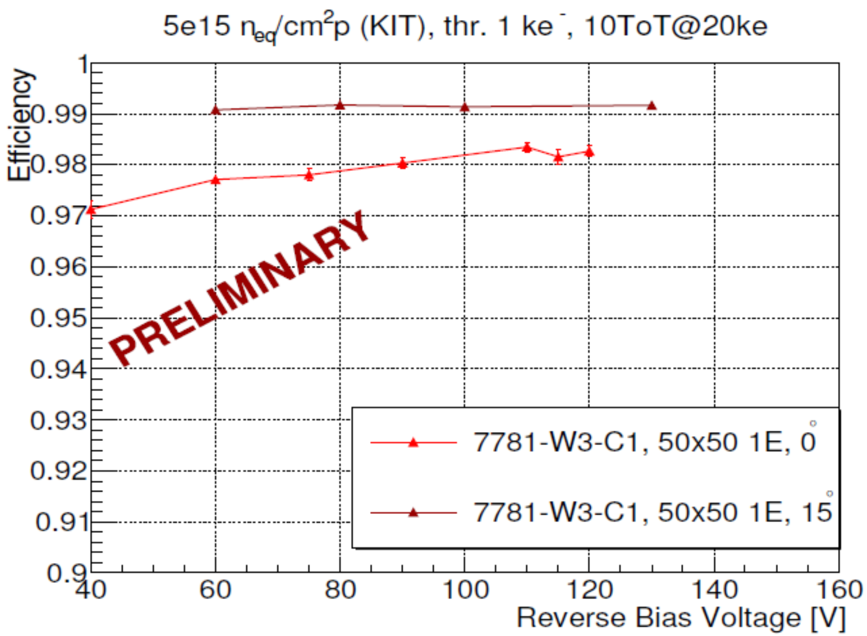


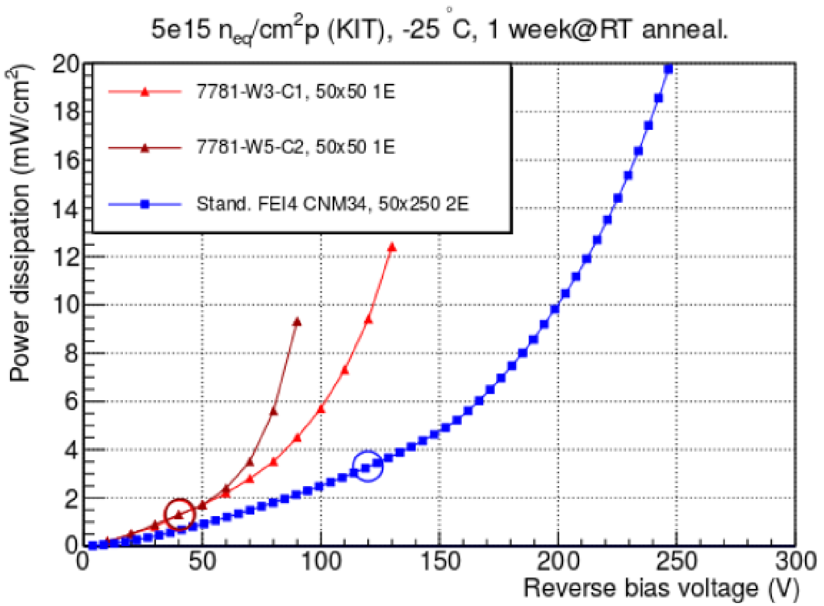


Uniform Irradiation to 5e15 n_{eq}/cm^2

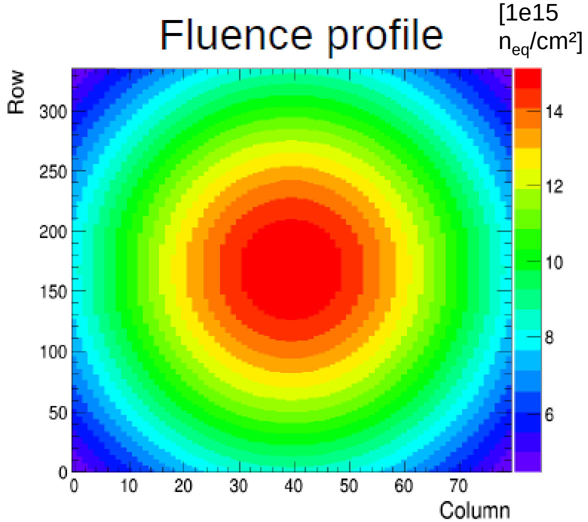


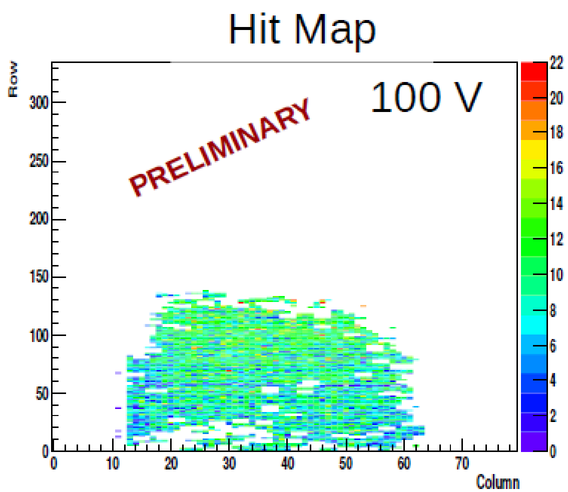
- 2 3D pixel devices of 50x50 µm²
- Irradiated uniformly to 5e15 n_{eq}/cm^2 at KIT
- Already 97% efficiency at 40 V (0° tilt)!
  - Compare to standard IBL/AFP FEI4: 120 V
  - Improves to 99% at 15° tilt
- Low V_{op} → advantage for power dissipation
  - 1.5 mW/cm²

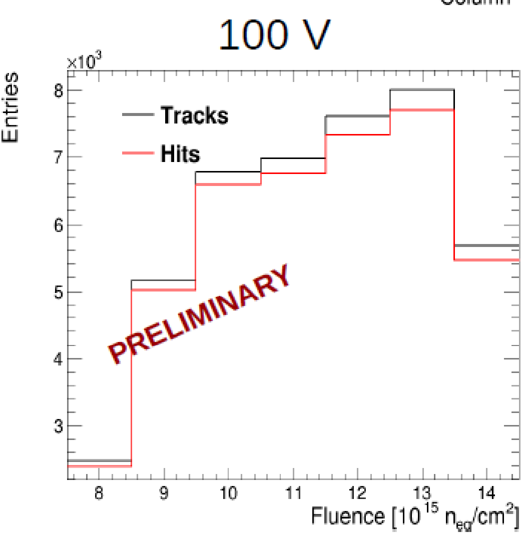


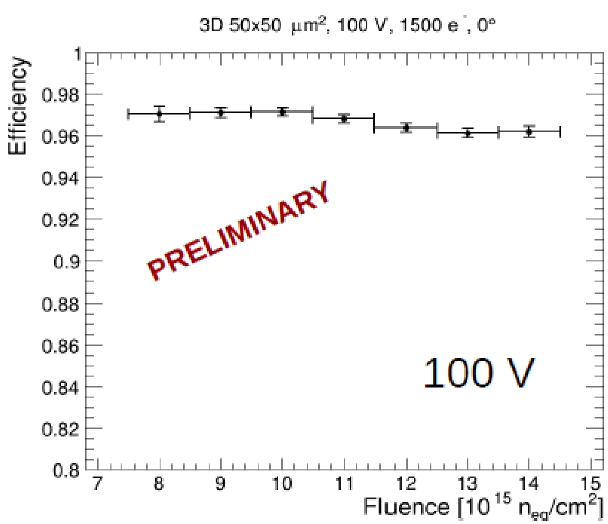


Non-Uniform Irradiation to 1.4e16 n_{eq}/cm^2



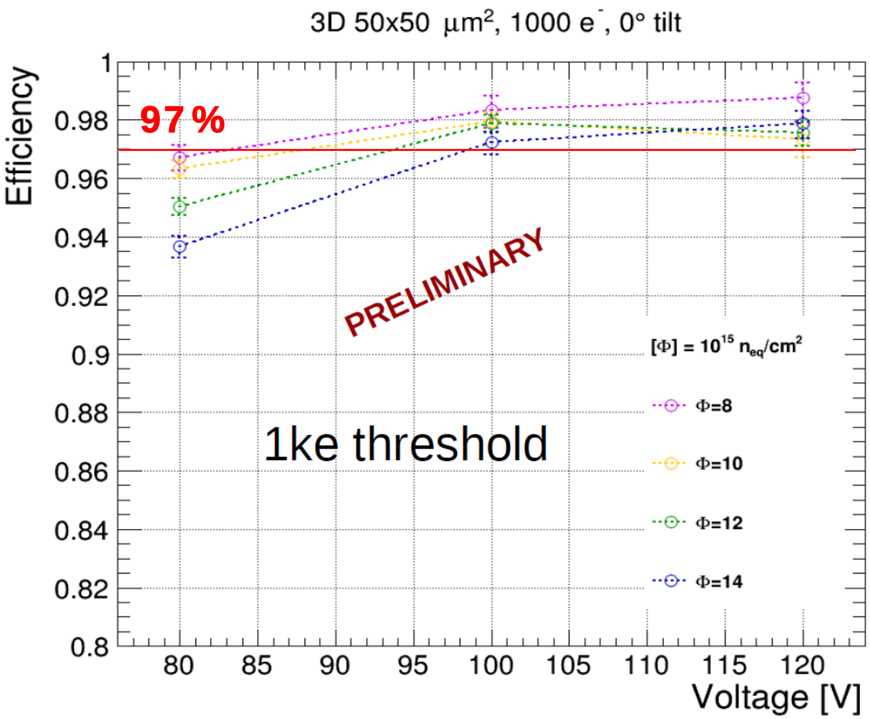


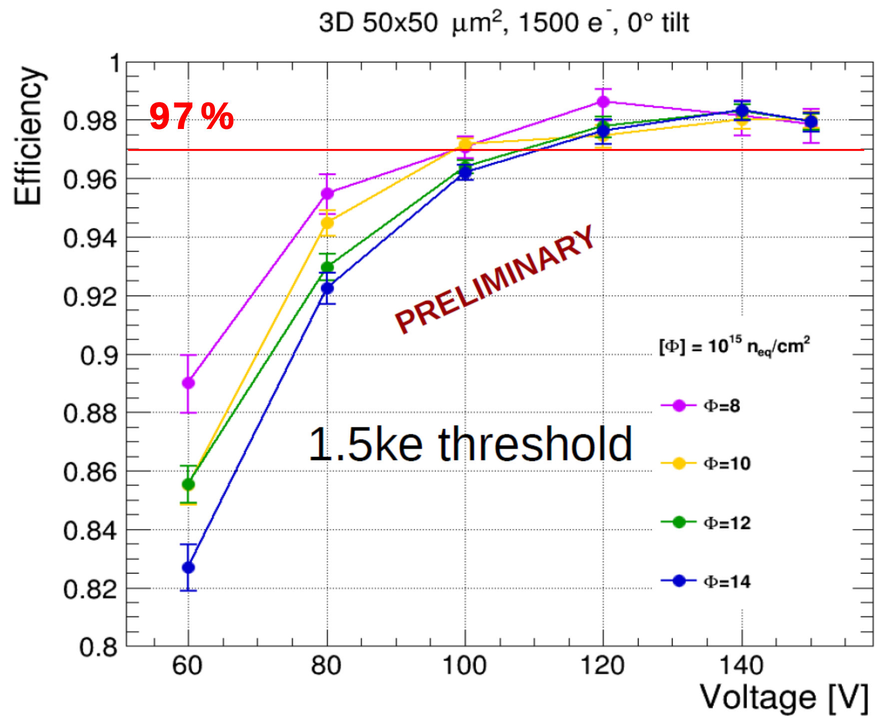




- Non-uniform irradiation at CERN-PS (23 GeV p) with 20x20 mm² beam
  - Can sample range of fluences on single device: 0.8 – 1.4e16 n_{eq}/cm^2
  - Estimation of systematic fluence uncertainty from variations of beam width and position by 1 mm:
    - 11% at 1.4e16 n_{eq}/cm^2
    - 24% at 8e15 n_{eq}/cm^2
- Only part of device with connected bumps (bad UBM)
  → Analysis in localised region

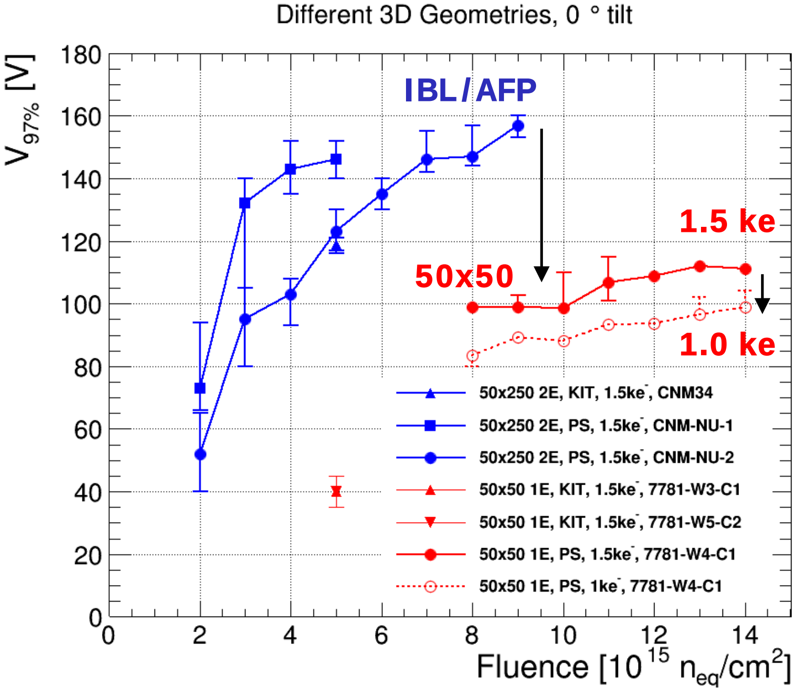
Efficiency for Non-Uniform Irradiation





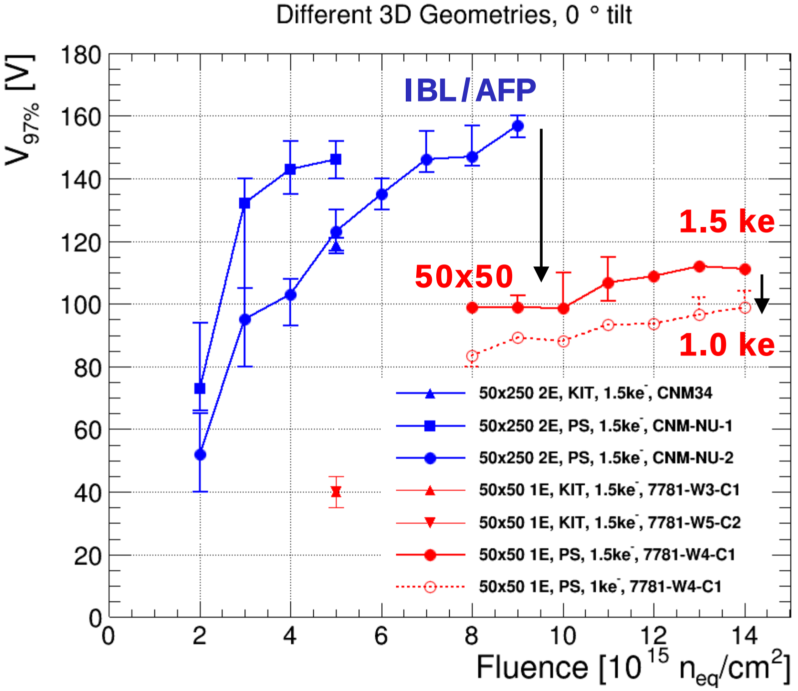
- Efficiency improves with lower threshold
- 97% efficiency already at 100 V (1 ke threshold) after 1.4e16 n_{eq}/cm^2!

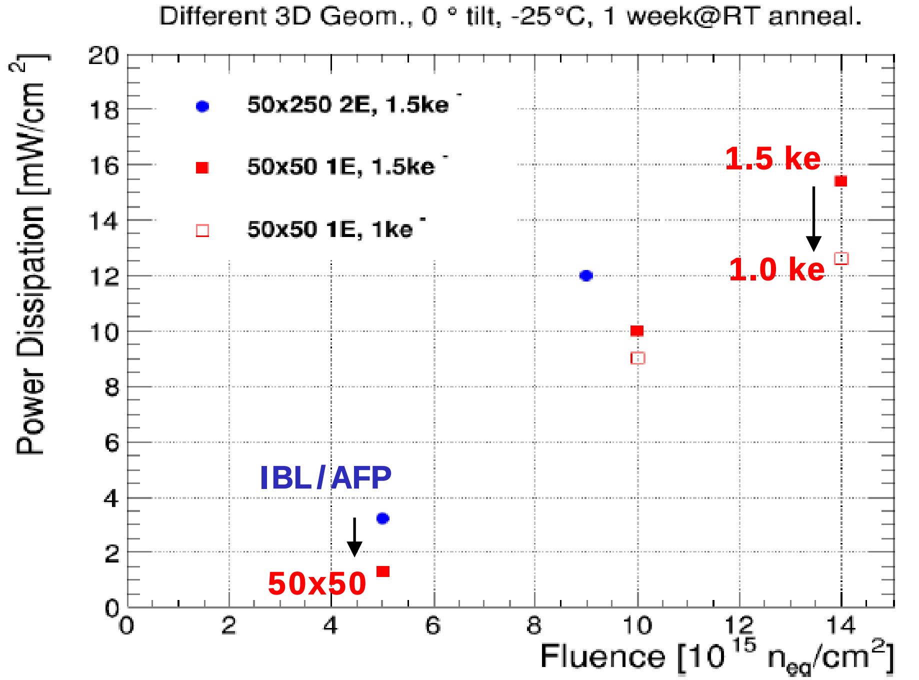
Comparison IBL to Small Pitch



- Highly improved operation voltage for 50x50 µm² 3D compared to IBL/AFP generation

Comparison IBL to Small Pitch





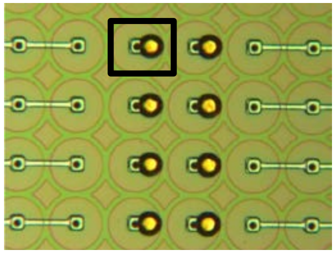
- Highly improved operation voltage for 50x50 µm² 3D compared to IBL/AFP generation
- Also improves power dissipation
  - Despite higher current for 50x50 µm² (still under investigation, might improve after optimisations)
  - 9 (13) mW/cm² at 1e16 (1.4e16) n_{eq}/cm²
  - Considerably lower than for 100 µm planar devices* with ≥25 mW/cm² at 1e16 n_{eq}/cm² (V_{op}=500 V)

* N. Savic et al., 28th RD50 Workshop, Torino, Italy, 6-8 June 2016

Conclusions and Outlook

- Studied IBL/AFP-generation 3D pixel detectors up to HL-LHC fluences
  - Already excellent radiation hardness
- Studied first CNM 3D production with small HL-LHC pixel size
  - 50x50 and 25x100 µm² matched to FEI4 chip
  - Highly reduced operational voltage and power dissipation wrt. IBL/AFP generation (and planar) also after irradiation
    - 100 V for 1.4e16 n_{eq}/cm²
  - Irradiation to higher fluences of 2-3e16 n_{eq}/cm² on-going

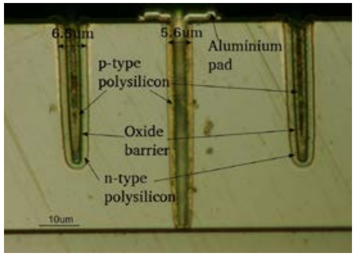
50x50 µm²



- Also productions and promising results from FBK and SINTEF

See talk by M. Meschini

- Single-sided thin (72-150 µm) 3D productions under way at CNM
  - Also with RD53 geometry



3D sensors excellent candidates for innermost pixel layer(s) at HL-LHC!

BACKUP